

Compliance with RoHS Directive

FEATURES

1. 2.5 mm wide ultra-slim two-piece connectors

The ultra-compact and slim body contributes to further miniaturization and functionality enhancement of target equipment.

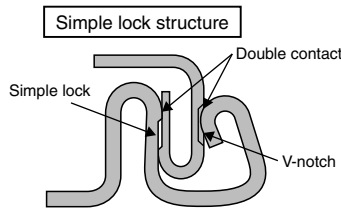
<Compared with our existing model (F4S, 40 contacts, when mated)>

- Width: 30% down
- Footprint: 30% down



2. "TOUGH CONTACT ADVANCED" structure adopted to ensure high resistance to various environments in spite of the ultra-slim and low profile body

3. The simple lock structure for good mating/unmating operation feel.



The connector gives the tactile feedback when inserted, allowing reliable mating.

4. Mated heights of 0.8 and 1.0 mm are available for the same foot pattern.

5. Connectors for inspection available (See page 47 for details of the structure)

APPLICATIONS

Recommended for board-to-FPC connections of mobile equipment, such as cellular phones, smart phones, notebook PCs, and portable music players

ORDERING INFORMATION

	AXE				2	4
5: Narrow Pitch Connector A4S (0.4 mm pitch) Socket						
6: Narrow Pitch Connector A4S (0.4 mm pitch) Header						
Number of contacts (2 digits)						
Mated height						
<Socket>						
1: For mated height 0.8/1.0 mm						
<Header>						
1: For mated height 0.8 mm						
2: For mated height 1.0 mm						
Functions						
2: Without positioning bosses						
Surface treatment (Contact portion / Terminal portion)						
<Socket>						
4: Ni plating on base, Au plating on surface (for Ni barrier available)						
<Header>						
4: Ni plating on base, Au plating on surface						

PRODUCT TYPES

Mated height	Number of contacts	Part number		Packing		
		Socket	Header	Inner carton (1-reel)	Outer carton	
0.8mm	10	AXE510124	AXE610124	5,000 pieces	10,000 pieces	
	12	AXE512124	AXE612124			
	14	AXE514124	AXE614124			
	16	AXE516124	AXE616124			
	18	AXE518124	AXE618124			
	20	AXE520124	AXE620124			
	22	AXE522124	AXE622124			
	24	AXE524124	AXE624124			
	26	AXE526124	AXE626124			
	28	AXE528124	AXE628124			
	30	AXE530124	AXE630124			
	32	AXE532124	AXE632124			
	34	AXE534124	AXE634124			
	36	AXE536124	AXE636124			
	38	AXE538124	AXE638124			
	40	AXE540124	AXE640124			
	44	AXE544124	AXE644124			
	50	AXE550124	AXE650124			
	1.0mm	54	AXE554124			AXE654124
		56	AXE556124			AXE656124
60		AXE560124	AXE660124			
64		AXE564124	AXE664124			
70		AXE570124	AXE670124			
80		AXE580124	AXE680124			
10		AXE510124	AXE610224			
12		AXE512124	AXE612224			
14		AXE514124	AXE614224			
20		AXE520124	AXE620224			
24		AXE524124	AXE624224			
26		AXE526124	AXE626224			
30		AXE530124	AXE630224			
32		AXE532124	AXE632224			
40		AXE540124	AXE640224			
44		AXE544124	AXE644224			
50	AXE550124	AXE650224				
54	AXE554124	AXE654224				
60	AXE560124	AXE660224				
70	AXE570124	AXE670224				
80	AXE580124	AXE680224				

Notes: 1. Order unit:

For mass production: in 1-inner carton (1-reel) units

Samples for mounting check: in 50-connector units. Please contact our sales office.

Samples: Small lot orders are possible. Please contact our sales office.

- The above part numbers are for connectors without positioning bosses, which are standard. When ordering connectors with positioning bosses, please contact our sales office.
- Please contact us for connectors having a number of contacts other than those listed above.

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SPECIFICATIONS

■ Characteristics

	Item	Specifications	Conditions
Electrical characteristics	Rated current	0.3A/contact (Max. 5 A at total contacts)	
	Rated voltage	60V AC/DC	
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1,000MΩ (initial)	Using 250V DC megger (applied for 1 min.)
	Contact resistance	Max. 90mΩ	Based on the contact resistance measurement method specified by JIS C 5402.
Mechanical characteristics	Composite insertion force	Max. 1.200N/contacts × contacts (initial)	
	Composite removal force	Min. 0.165N/contacts × contacts	
	Contact holding force (Socket contact)	Min. 0.20N/contacts	Measuring the maximum force. As the contact is axially pull out.
Environmental characteristics	Ambient temperature	-55°C to +85°C	No freezing at low temperatures. No dew condensation.
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals)	Infrared reflow soldering
		300°C within 5 sec. 350°C within 3 sec.	Soldering iron
	Storage temperature	-55°C to +85°C (product only) -40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Sequence 1. -55 ^{±3} °C, 30 minutes 2. ~, Max. 5 minutes 3. 85 ^{±3} °C, 30 minutes 4. ~, Max. 5 minutes
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 40±2°C, humidity 90 to 95% R.H.
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 35±2°C, saltwater concentration 5±1%
H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. 90mΩ	Bath temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.	
Lifetime characteristics	Insertion and removal life	30 times	Repeated insertion and removal speed of max. 200 times/hours
Unit weight		20-contact type: Socket: 0.02 g Header: 0.01 g	

■ Material and surface treatment

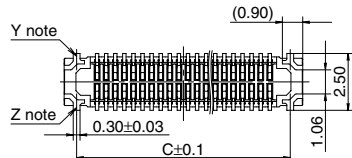
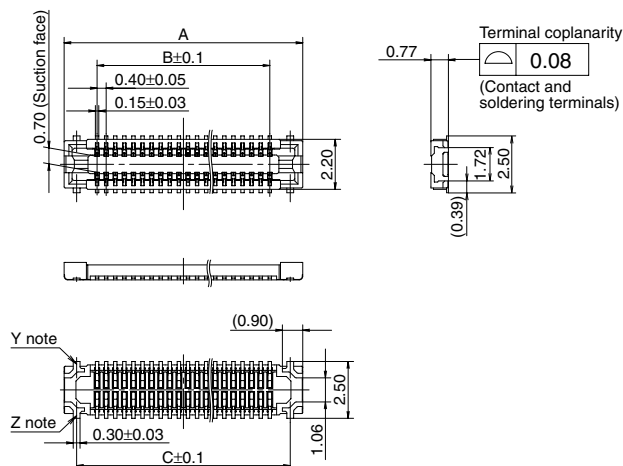
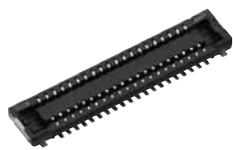
Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	—
Contact and Post	Copper alloy	Contact portion: Base: Ni plating Surface: Au plating Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Soldering terminals: Sockets: Base: Ni plating Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating Surface: Au plating (except the terminal tips)

DIMENSIONS (Unit: mm)

The CAD data of the products with a **CAD Data** mark can be downloaded from: <http://panasonic-electric-works.net/ac>

■ **Socket (Mated height: 0.8 mm/1.0 mm)**

CAD Data



General tolerance: ±0.2

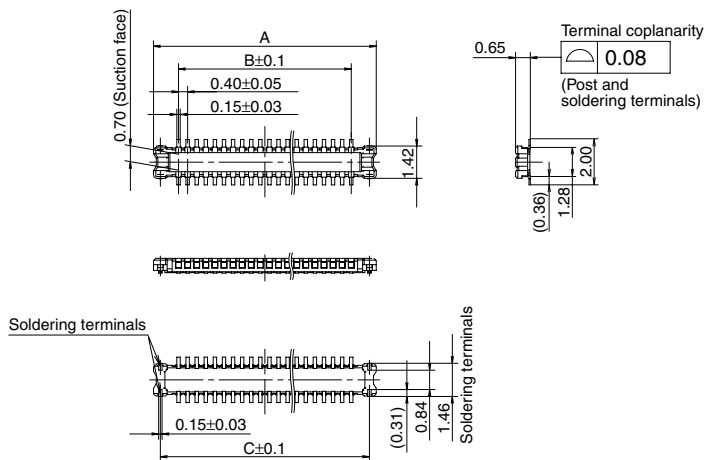
Note: Since the soldering terminals has a single-piece construction, sections Y and Z are electrically connected.

Dimension table (mm)

Number of contacts/ dimension	A	B	C
10	4.5	1.6	3.4
12	4.9	2.0	3.8
14	5.3	2.4	4.2
16	5.7	2.8	4.6
18	6.1	3.2	5.0
20	6.5	3.6	5.4
22	6.9	4.0	5.8
24	7.3	4.4	6.2
26	7.7	4.8	6.6
28	8.1	5.2	7.0
30	8.5	5.6	7.4
32	8.9	6.0	7.8
34	9.3	6.4	8.2
36	9.7	6.8	8.6
38	10.1	7.2	9.0
40	10.5	7.6	9.4
44	11.3	8.4	10.2
50	12.5	9.6	11.4
54	13.3	10.4	12.2
56	13.7	10.8	12.6
60	14.5	11.6	13.4
64	15.3	12.4	14.2
70	16.5	13.6	15.4
80	18.5	15.6	17.4

■ **Header (Mated height: 0.8 mm)**

CAD Data



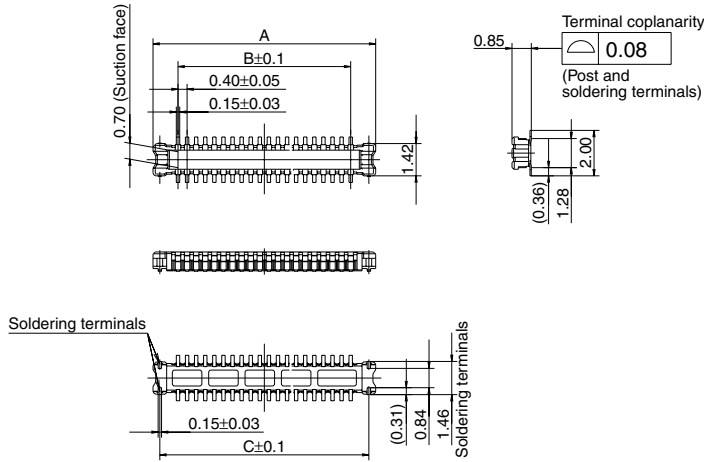
General tolerance: ±0.2

Dimension table (mm)

Number of contacts/ dimension	A	B	C
10	3.8	1.6	3.2
12	4.2	2.0	3.6
14	4.6	2.4	4.0
16	5.0	2.8	4.4
18	5.4	3.2	4.8
20	5.8	3.6	5.2
22	6.2	4.0	5.6
24	6.6	4.4	6.0
26	7.0	4.8	6.4
28	7.4	5.2	6.8
30	7.8	5.6	7.2
32	8.2	6.0	7.6
34	8.6	6.4	8.0
36	9.0	6.8	8.4
38	9.4	7.2	8.8
40	9.8	7.6	9.2
44	10.6	8.4	10.0
50	11.8	9.6	11.2
54	12.6	10.4	12.0
56	13.0	10.8	12.4
60	13.8	11.6	13.2
64	14.6	12.4	14.0
70	15.8	13.6	15.2
80	17.8	15.6	17.2

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■ Header (Mated height: 1.0 mm)

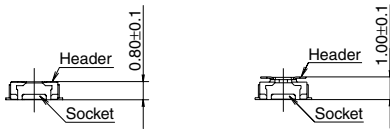


Dimension table (mm)

Number of contacts/ dimension	A	B	C
10	3.8	1.6	3.2
12	4.2	2.0	3.6
14	4.6	2.4	4.0
20	5.8	3.6	5.2
24	6.6	4.4	6.0
26	7.0	4.8	6.4
30	7.8	5.6	7.2
32	8.2	6.0	7.6
40	9.8	7.6	9.2
44	10.6	8.4	10.0
50	11.8	9.6	11.2
54	12.6	10.4	12.0
60	13.8	11.6	13.2
70	15.8	13.6	15.2
80	17.8	15.6	17.2

General tolerance: ±0.2

■ Socket and Header are mated



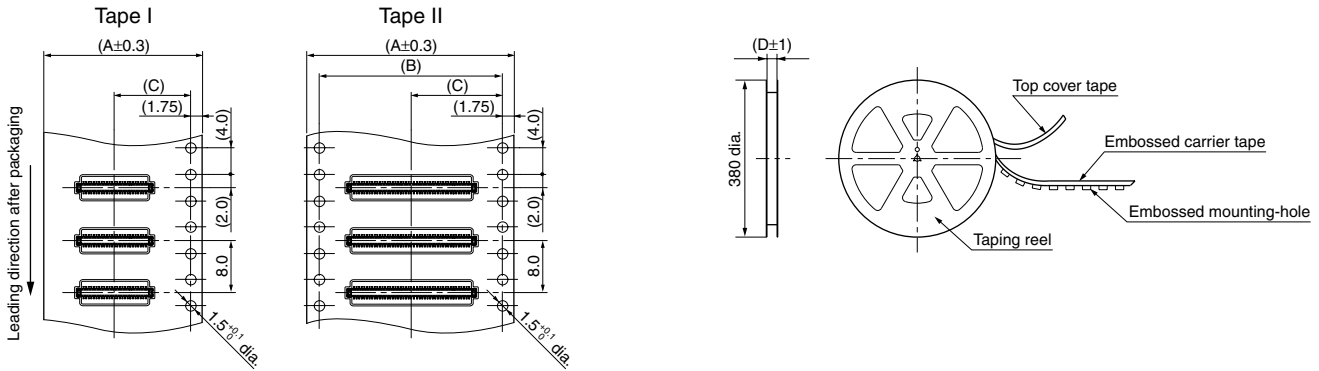
EMBOSSED TAPE DIMENSIONS (Unit: mm) (Common for respective contact types, sockets and headers)

■ Specifications for taping

(In accordance with JIS C 0806-1990. However, not applied to the mounting-hole pitch of some connectors.)

■ Specifications for the plastic reel

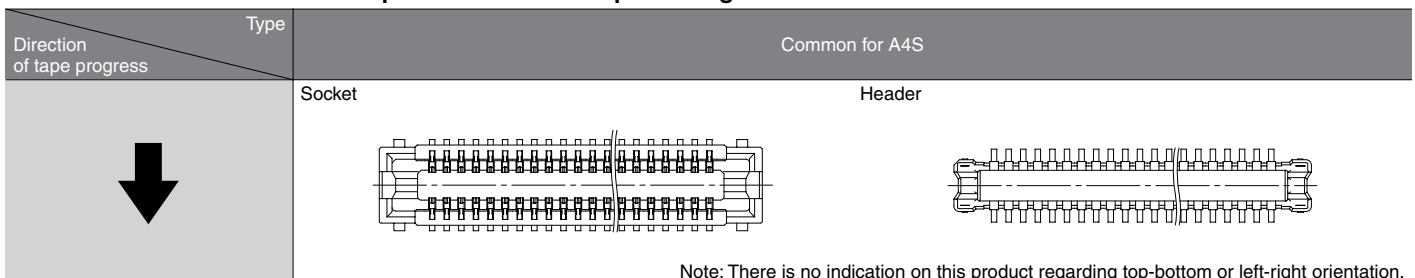
(In accordance with EIAJ ET-7200B.)



■ Dimension table (Unit: mm)

Type/Mated height	Number of contacts	Type of taping	A	B	C	D	Quantity per reel
Common for sockets and headers 0.8 mm/1.0 mm	24 or less	Tape I	16.0	—	7.5	17.4	5,000
	26 to 70	Tape I	24.0	—	11.5	25.4	5,000
	80	Tape II	32.0	28.4	14.2	33.4	5,000

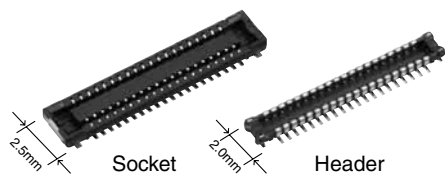
■ Connector orientation with respect to embossed tape feeding direction



Note: There is no indication on this product regarding top-bottom or left-right orientation.



For board-to-FPC	<h1>A4S Series</h1>
Connectors for inspection usage (0.4mm pitch)	



Compliance with RoHS Directive

FEATURES

- 3,000 insertion and removals (when as recommended)**
- Same external dimensions and foot pattern as standard type.**
- Improved mating**
Insertion and removal have become easier due to a reduction in the mating retention force required by the simple locking structure and also in the amount of force needed for insertion and removal. (We cannot warrant anything regarding mating retention.)

APPLICATIONS

Ideal for module unit inspection and equipment assembly inspection

TABLE OF PRODUCT TYPES

☆: Available for sale

Product name	Number of contacts																							
A4S for inspection	10	12	14	16	18	20	22	24	26	28	30	32	34	36	38	40	44	50	54	56	60	64	70	80
	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆	☆

- Notes: 1. Please inquire about numbers of contacts other than those given above.
 2. Please inquire with us regarding delivery times.
 3. Please keep the minimum unit for ordering no less than 50 pieces per lot.
 4. Please inquire for further information.

PRODUCT TYPES

Specifications		Part No.	Specifications		Part No.
Socket	Without positioning bosses	AXE5E**26	Header	Without positioning bosses	AXE6E**26

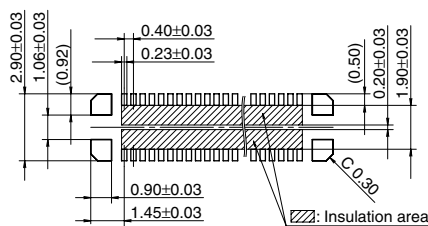
Note: When placing an order, substitute the "*" (asterisk) in the above part number with the number of contacts for the required connector.

NOTES

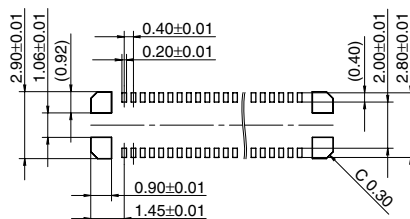
Recommended PC board and metal mask patterns

Appropriate control of solder amount is required to minimize solder bridges and other defects for connectors with 0.4-mm or 0.5-mm pitch terminals, which require high-density mounting. Refer to the right-hand drawing for recommended patterns.

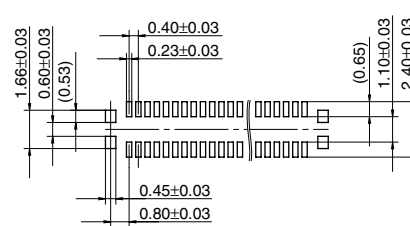
• Socket (Mated height: 0.8mm/1.0mm) Recommended PC board pattern (TOP VIEW)



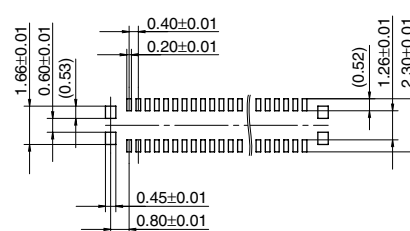
Recommended metal mask opening pattern
 Metal mask thickness: When 120µm
 (Terminal opening ratio: 70%)
 (Metal-part opening ratio: 100%)



• Header (Mated height: 0.8mm/1.0mm) Recommended PC board pattern (TOP VIEW)



Recommended metal mask opening pattern
 Metal mask thickness: When 120µm
 (Terminal opening ratio: 70%)
 (Metal-part opening ratio: 100%)



For other details, please verify with the product specification sheets.

NOTES FOR USING ADVANCED SERIES NARROW-PITCH CONNECTORS (Common)

■ Connector mounting

In case the connector is picked up by chucking during mounting, an excessive moulder chucking force may deform the molded or metal part of the connector. Consult us in advance if chucking is to be applied.

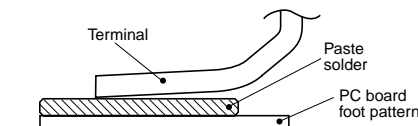
■ Soldering

1) Manual soldering.

- Due to the low profile, if an excessive amount of solder is applied to this product during manual soldering, the solder may creep up to near the contact points, or interference by solder may cause imperfect contact.
- Make sure that the soldering iron tip is heated within the temperature and time limits indicated in the specifications.
- Flux from the solder wire may adhere to the contact surfaces during soldering operations. After soldering, carefully check the contact surfaces and clean off any flux before use.
- Be aware that a load applied to the connector terminals while soldering may displace the contact.
- Thoroughly clean the iron tip.

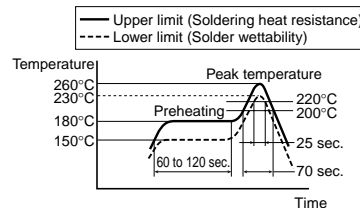
2) Reflow soldering

- Screen-printing is recommended for printing paste solder.
 - To determine the relationship between the screen opening area and the PC-board foot pattern area, refer to the diagrams in the recommended patterns for PC boards and metal masks. Make sure to use the terminal tip as a reference position when setting.
- Avoid an excessive amount of solder from being applied, otherwise, interference by the solder will cause an imperfect contact.



- Consult us when using a screen-printing thickness other than that recommended.
- Depending on the size of the connector being used, self alignment may not be possible. Accordingly, carefully position the terminal with the PC board pattern.
- The recommended reflow temperature profile is given in the figure below

Recommended reflow temperature profile

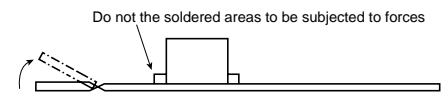


- The temperature is measured on the surface of the PC board near the connector terminal.
 - Some solder and flux types may cause serious solder creeping. Take the solder and flux characteristics into consideration when setting the reflow soldering conditions.
 - When performing reflow soldering on the back of the PC board after reflow soldering the connector, secure the connector using, for example, an adhesive (Double reflow soldering on the same side is possible)
- 3) Reworking on a soldered portion
- Finish reworking in one operation.
 - For reworking of the solder bridge, use a soldering iron with a flat tip. Do not add flux, otherwise, the flux may creep to the contact parts.
 - Use a soldering iron whose tip temperature is within the temperature range specified in the specifications.

■ Do not drop the product or handle it carelessly. Otherwise, the terminals may become deformed due to excessive force or the solderability during reflow soldering may degrade.

■ Do not insert or remove the connector when it is not soldered. Also, forcibly applied external pressure on the terminals can weaken the adherence of the terminals to the molded part or cause the terminals to lose their evenness.

■ When cutting or bending the PC board after mounting the connector, be careful that the soldered sections are subjected to excessive forces.



■ Notes when using a FPC.

- When the connector is soldered to an FPC board, during its insertion and removal procedures, forces may be applied to the terminals and cause the soldering to come off. It is recommended to use a reinforcement board on the backside of the FPC board to which the connector is being connected. Make sure that the reinforcing plate is larger than the outline of the recommended PC board pattern (Outline + approx. 1 mm). The reinforcing plate is made of SUS, glass epoxy or polyimide that is 0.2 to 0.3 mm thick.

This connector employs a simple locking structure. However, the connector may come off depending on the size and weight of the FPC, layout and reaction force of FPC, or by drop impact. Make sure to fully check the equipment's condition. To prevent any problem with loose connectors, adopt measures to prevent the connector from coming off inside the equipment.

■ Other Notes

When coating the PC board after soldering the connector to prevent the deterioration of insulation, perform the coating in such a way so that the coating does not get on the connector. The connectors are not meant to be used for switching.

For other details, please verify with the product specification sheets.